

Influences of initial bulk traps on Negative Bias Temperature Instability of HfSiON

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Introduction

HfSiON film is one of the promising gate dielectrics to replace conventional SiO₂/SiON films in future ULSIs. There are some reports about the NBTI in HfSiON, but the time dependence of NBT-degradation reported are not unique[1,2]. It has an important impact for the lifetime projection because the predicted lifetime may change depending on stress time dependence. In this paper, we investigate the influence of initial traps for the stress time dependence of ΔV_{th} under NBT-stress and propose the correct lifetime projection with consideration of the influence of initial traps.

Experimental

The devices used in this study were p+poly/pMISFET with HfSiON gate dielectrics fabricated by the conventional CMOS process. Hf concentration is about 50% (Hf/(Hf+Si)). The thickness of gate HfSiON film was around 4.5 nm and amorphous structures were confirmed by TEM observation. Threshold voltage (V_{th}) and Interface-state densities (Dit) were measured under negative constant voltage stress. The V_{th} was estimated by Id-Vg measurement and Dit was evaluated by the charge-pumping measurement.

Results and Discussion

It has been reported that ΔV_{th} and ΔD_{it} have a power law dependence of stress time ($\Delta V_{th} (\Delta D_{it}) = A \cdot t^B$) for SiO₂ and it was explained by reaction-diffusion model[3]. Figure 1 shows the NBT-stress time dependence of ΔV_{th} and ΔD_{it} for HfSiON and SiO₂ at Eox = 7MV/cm and Temp.=125 °C. In SiO₂, time dependence factor B for ΔV_{th} and ΔD_{it} was almost the same (~0.25) and it indicated that ΔV_{th} was caused by generated interface traps. However, in HfSiON, B of ΔV_{th} are smaller than that of ΔD_{it} . The time dependence factor B has an important impact for the lifetime projection. If the estimated B is smaller than real B , we can overestimate the device lifetime. In order to investigate the origin of small B of ΔV_{th} in HfSiON, we compared the NBT degradation behavior of ΔV_{th} and ΔD_{it} of SiO₂ and HfSiON. Figure 2 shows the stress time dependence of the normalized ΔV_{th} and ΔD_{it} of SiO₂ and HfSiON. The large jump was observed for the only ΔV_{th} of HfSiON at initial NBT-stress. Then, We focused on the effects of this initial jump for the time dependence of ΔV_{th} . Figure 3 shows the calculated results of the time dependence of ΔV_{th} ; $\Delta V_{th} = A \cdot t^B + \Delta V_{th,ini}$ with several $\Delta V_{th,ini}$. Here, $\Delta V_{th,ini}$ is initial jump of ΔV_{th} . As shown in Fig.3, B depends on the $\Delta V_{th,ini}$ in short time region. On the other hand, the sample with small $\Delta V_{th,ini}$ shows no decrease of B . These results indicate that the large initial jump of ΔV_{th} causes the small B , especially at short time. Therefore, the lack of universality in reported value of B is considered to be due to this initial jump.

The large jump of ΔV_{th} in HfSiON can be caused by much trapped holes at initial NBT-stress, because large amounts of initial traps are included in HfSiON. In order to confirm the relation between stress time dependence of ΔV_{th} and initial bulk traps, we investigate the stress time dependence of ΔV_{th} for four samples with different initial trap density. The initial trap densities were controlled by positive stresses. Table.1 shows the stress conditions of each sample. The Dit did not increase under

these stress conditions. Figure 4 shows the SILC characteristics and CV characteristics of each sample. Though Dit is independent of positive stress (Table.1), both SILC and CV hysteresis increase with increasing Qinj, which indicates that bulk traps increase in the films. Figure 5 shows the stress time dependence of ΔD_{it} and ΔV_{th} for each sample under NBT-stress. Stress conditions were Vg=-2.5V, Temp.=125°C. Stress time dependence of ΔV_{th} for the sample with bulk traps is similar to that for sample with initial jump (see Fig.3). The small time dependence of ΔV_{th} was observed for the sample with large Qinj, in short time region. The solid lines are the fit using $\Delta V_{th} = A \cdot t^B + \Delta V_{th,ini}$, where $\Delta V_{th,ini}$ was experimental data of the initial jump of ΔV_{th} . ΔD_{it} of each sample shows almost same stress-time dependence, as shown in Fig.5(B). The solid line is the fit using $\Delta D_{it} = A \cdot t^B$; $B \sim 0.25$. Figure 6 shows the fitting parameter A , B of ΔV_{th} for each sample in Fig.5(A). A , B are independent of samples; $A \sim 1 \times 10^{-2}$, $B \sim 0.24$. Here, B for ΔV_{th} without the influence of initial bulk traps is almost the same as B for ΔD_{it} . Figure 7 shows the stress time dependence of ΔV_{th} for each sample after filling in initial traps. In order to fill in initial traps, Vg=-2.5V were applied at very short time before NBTI measurement. Using this measurement, ΔV_{th} of all samples shows unique curve. These results indicate that the stress time dependence of ΔV_{th} except the influence of initial bulk traps is similar to that of ΔD_{it} . Figure 8 (A) shows the temperature dependence of ΔV_{th} and ΔD_{it} of SiO₂[4]. The activation energies of both ΔV_{th} and ΔD_{it} are about ~0.2eV. According to this result, the origins of ΔD_{it} and ΔV_{th} are considered to be the same[4]. Figure 8 (B) shows the temperature dependence of ΔV_{th} and ΔD_{it} of HfSiON. NBT-Stress was applied at Vg = -2.5V and Temp. = 25~175°C for 5120sec. The activation energies of ΔV_{th} and ΔD_{it} are estimated as about 0.07eV and 0.1eV respectively. These ΔV_{th} characteristics included the influence of initial bulk traps. However, the activation energy of ΔV_{th} without the influence of initial bulk trap is estimated as about 0.09eV and is almost the same value as that of ΔD_{it} . From these results, it was found that the ΔV_{th} was mainly caused by ΔD_{it} , except the influence of initial bulk traps, in HfSiON. The differences in NBT-degradation behavior of HfSiON from SiO₂ were caused by the influence of initial bulk traps.

Conclusion

The influence of initial bulk traps on V_{th} shift under NBT-stress has been investigated. The existence of large amounts of initial traps strongly influence on the time dependence and temperature dependence of ΔV_{th} . Especially in HfSiON, the strong influence of bulk traps was included in NBT-degradation characteristics. We need to estimate the NBTI-lifetime with consideration of the effect of initial bulk traps, especially in short time measurement.

Reference

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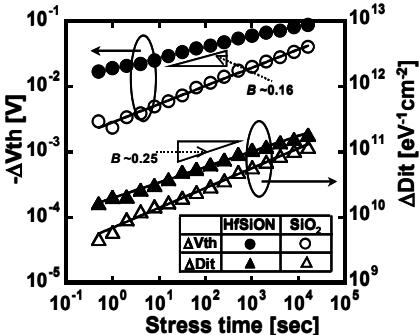


Fig.1 Stress time dependence of ΔV_{th} and ΔD_{it} of HfSiON and SiO_2 under NBT-stress. NBT-stress was performed at 125°C under $E_{ox}=7MV/cm$. The time dependence factor B for ΔV_{th} is smaller than that for ΔD_{it} in HfSiON.

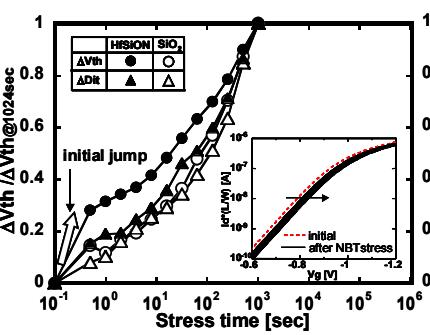


Fig.2 Stress time dependence of normalized ΔV_{th} and ΔD_{it} of HfSiON and SiO_2 . The V_{th} of HfSiON jumped up at initial NBT-stress. The inset shows the initial and stressed $Id-V_g$ curve. The large V_{th} shift was observed at initial NBT-stress.

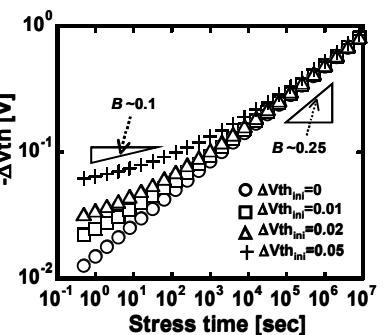


Fig.3 Stress time dependence of ΔV_{th} of the sample with initial jump of $V_{th}(\Delta V_{th_{ini}})$. Small time dependences were observed for the sample with large $\Delta V_{th_{ini}}$ at short stress time.

Table.1 Stress conditions, SILC, CV hysteresis and Dit of each sample.

Sample	Stress voltage[V]	$Q_{inj}[C/cm^2]$	SILC ($\Delta J/J_0 @ V_g-V_{th}=-0.5V$)	$V_{phys}[V]$	Dit [$eV^{-1}cm^{-2}$]
(a)	0	0	0	0.019	6.2×10^{11}
(b)	2.0	109.3	0.53	0.038	6.4×10^{11}
(c)	2.3	386.2	2.14	0.042	5.9×10^{11}
(d)	2.5	628.4	10.04	0.061	5.8×10^{11}

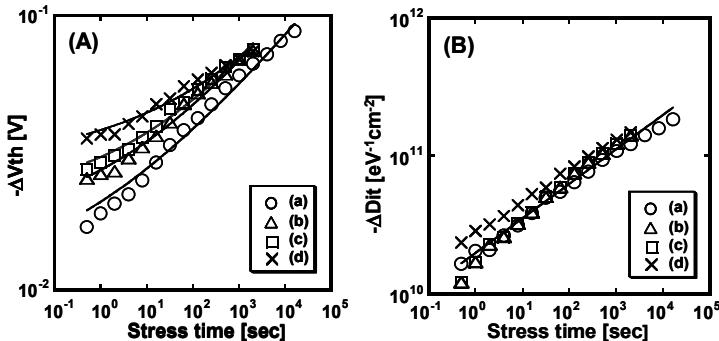


Fig.5 Stress time dependences of (A) ΔV_{th} and (B) ΔD_{it} for each sample under NBT-stress. (A) Stress time dependence of ΔV_{th} of sample with bulk traps is similar to that of sample with initial jump (see Fig.3). The small time dependence of ΔV_{th} was observed for the sample with large Q_{inj} , in the short stress time region. The solid lines are the fit using $\Delta V_{th}=A t^B+\Delta V_{th_{ini}}$, where $\Delta V_{th_{ini}}$ was experimental data of the initial jump of ΔV_{th} . (B) ΔD_{it} of each sample shows almost the same stress-time dependence. The solid line is the fit using $\Delta D_{it}=A' t^B$. Stress time factor B is about 0.25.

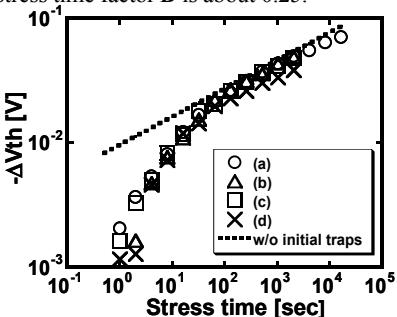


Fig.7 Stress time dependence of ΔV_{th} for each sample. ΔV_{th} were measured after filling in initial traps. The dotted line shows $\Delta V_{th}=1 \times 10^{-2} t^{0.24}$ without $\Delta V_{th_{ini}}$, which are obtained from Fig.6. Except the influence of bulk traps, the stress time dependence of ΔV_{th} show unique curve. The deviation from the dotted line at short stress time may be due to additional stress in trap filling process.

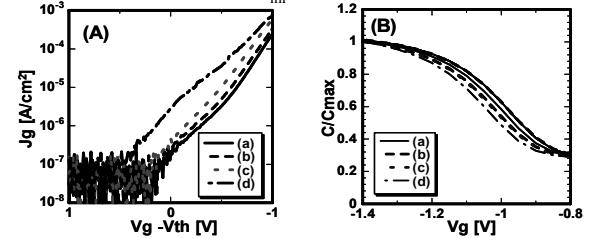


Fig.4 (A) J_g-V_g characteristics and (B) CV characteristics of each sample. SILC were observed for samples (b) ~ (d) and CV hysteresis were observed for all samples. Though D_{it} is independent of positive stress, both SILC and CV hysteresis increase with increasing Q_{inj} , which indicates that bulk traps increase in the films.

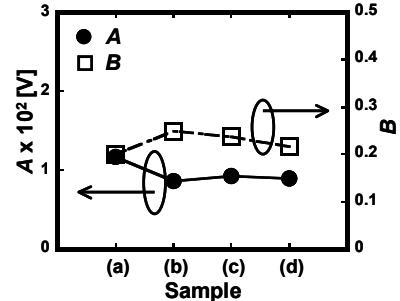


Fig.6 The fitting parameter A , B of ΔV_{th} for each sample in fig.5(B). A , B are almost same values; $A \sim 1 \times 10^{-2}$, $B \sim 0.24$. The stress time factor B for ΔV_{th} except the influence of initial bulk trap almost the same as the B for ΔD_{it} (~ 0.25 (see Fig.5(A)).

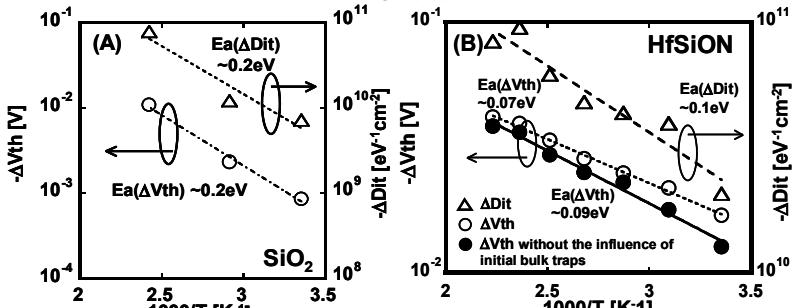


Fig.8 (A) Temperature dependence of ΔV_{th} and ΔD_{it} of SiO_2 [4]. The activation energies of both ΔV_{th} and ΔD_{it} are about 0.2eV. (B) Temperature dependence of ΔV_{th} and ΔD_{it} of HfSiON. NBT-Stress was applied under $V_g=-2.5V$ for 5120sec. The activation energies of ΔV_{th} and ΔD_{it} are estimated as about 0.07eV and 0.1eV respectively. Closed symbol shows the ΔV_{th} without the influence of initial bulk traps, whose activation energy is estimated as about 0.09eV and is almost the same value as that of ΔD_{it} .